TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L^2 - π -MOSV)

2SK3387

Switching Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain-source ON resistance: RDS (ON) = $0.08 \Omega(\text{typ.})$

• High forward transfer admittance: $|Y_{fs}| = 17 \text{ S (typ.)}$

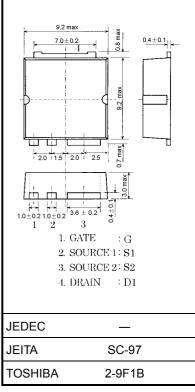
• Low leakage current: $I_{DSS} = 100 \mu A (V_{DS} = 150 V)$

• Enhancement-mode: $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	150	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	150	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	18	Α	
Diam curient	Pulse (Note 1)	I_{DP}	54		
Drain power dissipation	n (Tc = 25°C)	P _D	100	W	
Single pulse avalanche energy (Note 2)		E _{AS}	176	mJ	
Avalanche current		I _{AR}	18	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	−55~150	°C	

Unit: mm



Weight: 0.74 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: $V_{DD} = 50 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), $L = 800 \mu\text{H}$, $R_G = 25 \Omega$, $I_{AR} = 18 \text{ A}$

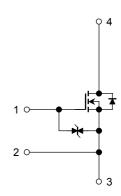
Note 3: Repetitive rating: pulse width limited by max junction temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

Notice:

Please use the S1 pin for gate input signal return. Make sure that the main current flows into S2 pin.





Electrical Characteristics (Note 4) (Ta = 25°C)

Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage curr	ent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$		_	±10	μА	
Drain cut-off curre	nt	I _{DSS}	$V_{DS} = 150 \text{ V}, V_{GS} = 0 \text{ V}$			100	μА	
Drain-source brea	kdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	150			V	
Gate threshold vo	ltage	V_{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	0.8	_	2.0	V	
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 4 \text{ V}, I_D = 9 \text{ A}$		0.09	0.18	Ω	
		20 (01.1)	V _{GS} = 10 V, I _D = 9 A		0.08	0.12		
Forward transfer a	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 9 \text{ A}$	10	17		S	
Input capacitance		C _{iss}			1380	_		
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		200		pF	
Output capacitance		Coss		_	610	_		
	Rise time	t _r	10 V		12			
Switching time	Turn-on time	t _{on}	$\begin{array}{c c} & O & V & \downarrow & \downarrow \\ & G & \bigcirc & \downarrow & \downarrow & \downarrow \\ & G & \bigcirc & \downarrow & \downarrow & \downarrow \\ & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & & & & & \downarrow & \downarrow \\ & \downarrow & \downarrow & \downarrow \\ $		20		ns	
Switching time	Fall time	t _f	$S_1 \stackrel{\stackrel{\sim}{\downarrow}}{\longrightarrow} S_2 \stackrel{\circ}{\downarrow} V_{DD} \simeq 100 \text{ V}$		12		115	
	Turn-off time	t _{off}	Duty ≤ 1%, t _W = 10 μs		68			
Total gate charge (gate-source plus gate-drain) Qg		Qg			57		nC	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 120 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 18 \text{ A}$	_	43	_	nC	
Gate-drain ("miller") charge		Q _{gd}		_	14	_	nC	

Note 4: Please connect the S1 pin and S2 pin, and then ground the connected pin. (However, while switching times are measured, please don't connect and ground it.)

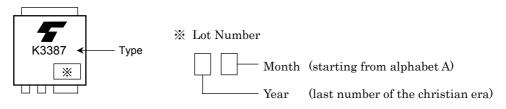
Source-Drain Diode Ratings and Characteristics (Note 5) (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current	(Note 1, 5)	I _{DR} 1	_	_	_	18	Α
Pulse drain reverse current	(Note 1, 5)	I _{DRP} 1	_	_	_	54	Α
Continuous drain reverse current	(Note 1, 5)	I _{DR} 2	_	_	_	1	Α
Pulse drain reverse current	(Note 1, 5)	I _{DRP} 2	_	_	_	4	Α
Diode forward voltage		V _{DS2F}	I _{DR1} = 18 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time		t _{rr}	I _{DR} = 18 A, V _{GS} = 0 V,	_	185	_	ns
Reverse recovery charge		Q _{rr}	dl _{DR} /dt = 100 A/μs	_	1.3	_	μС

Note 5: drain, flowing current value between the S2 pin, open the S1 pin drain, flowing current value between the S1 pin, open the S2 pin

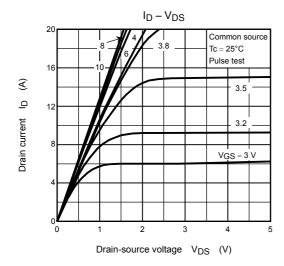
Unless otherwise specified, please connect the S1 and S2 pins, and then ground the connected pin.

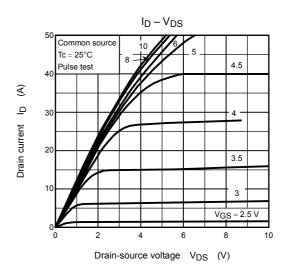
Marking

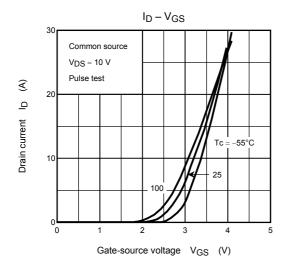


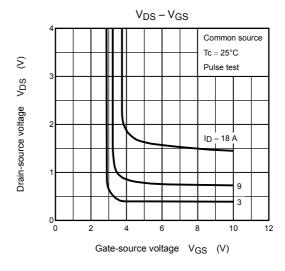
2

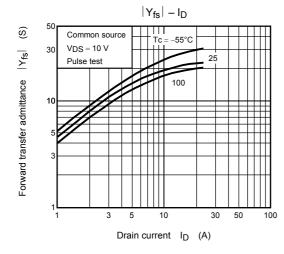
2002-07-22

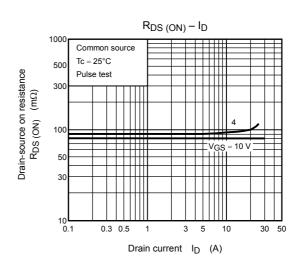




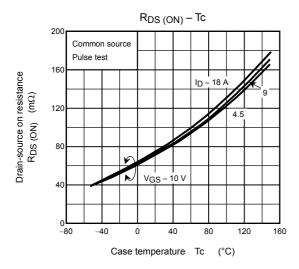


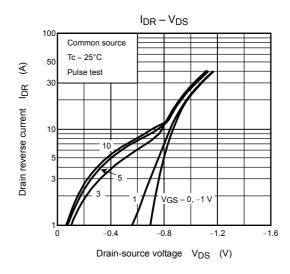


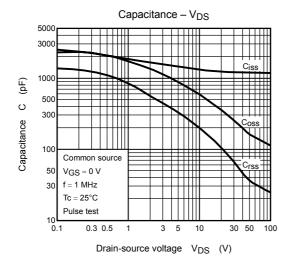


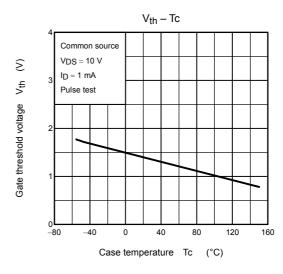


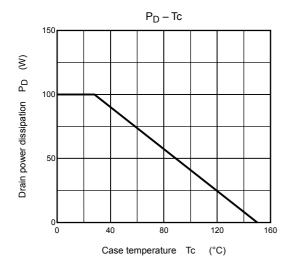
3

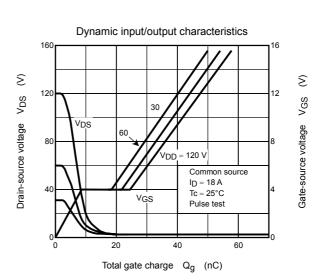




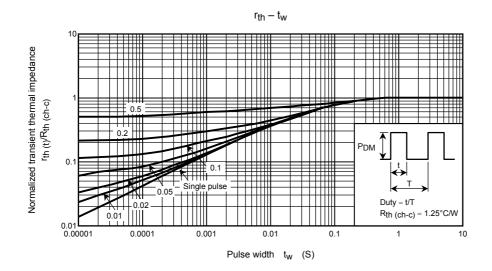


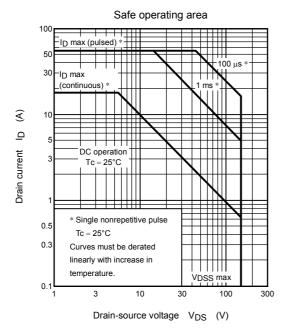


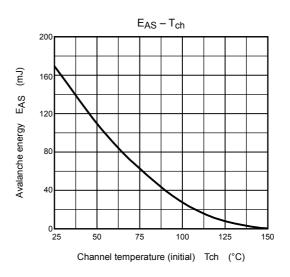


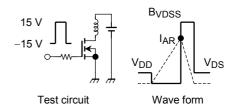


4









$$R_G = 25~\Omega$$

$$V_{DD} = 50~V,~L = 0.8~mH$$

$$\mathsf{EAS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left(\frac{\mathsf{BVDSS}}{\mathsf{BVDSS} - \mathsf{VDD}} \right)$$

RESTRICTIONS ON PRODUCT USE

000707EAA

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc..
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The information contained herein is presented only as a guide for the applications of our products. No
 responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other
 rights of the third parties which may result from its use. No license is granted by implication or otherwise under
 any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.